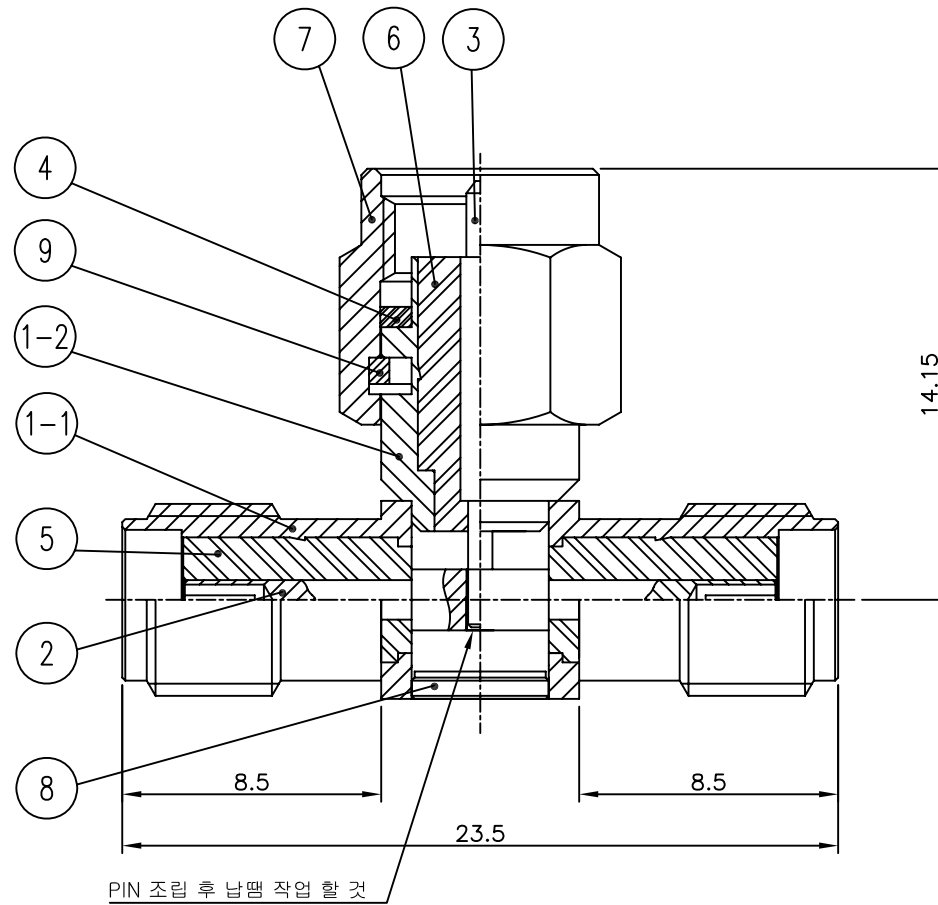


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2019.01.11.



9	SPRING RING	1	SUS	Passivated	DSR00002-5/1	
8	COVER	1	MBsBD C3604BD-F	Gold Plate	DCO00021-5/1	
7	COUPLING CAP	1	MBsBD C3604BD-F	Gold Plate	DCU00005-5/5	
6	INSULATOR	1	TEFLON		DIN03024-N/1	
5	INSULATOR	2	TEFLON		DIN02177-N/1	
4	GASKET	1	SILICON		DGK00004-N/1	
3	CONTACT	1	MBsBD C3604BD-F	Gold Plate	DCT00309-5/2	
2	CONTACT	1	BeCu C17300	Gold Plate	DCT00099-5/2	
1	1-2 BODY	1	MBsBD C3604BD-F	Gold Plate	DBB00480-5/1	DBD00255-1/2
	1-1 BODY (A)	1	MBsBD C3604BD-F	Gold Plate		DBD00125-3/2
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE	

★ 조립방법

- ①번 BODY에 한쪽 ⑤번 절연체, ②번 PIN 순으로 조립 후 반대쪽 ⑤번 절연체 조립한다.
(PIN 방향 주의)
- ①번 BODY에 ⑥번 절연체 조립 후 ③번 PIN 조립한다.
- ②번 PIN + ③번 PIN 조립 부위에 납땜 작업한다.
- ⑧번 COVER 조립한다.
- ④번 GASKET, ⑨번 RING, ⑦번 CAP 조립한다.

TOLERANCE	Decimal	DATE 2019. 01. 11.	
	Angle	APPROVED BY	I.C.KIM
MATERIAL		CHECKED BY	
		DRAWN BY	S.Y.EUN
FINISH		SCALE	UNIT
		4/1	mm

		RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
		KJ COMTECH CO.,LTD.	
TITLE		SMA50 TA-JPJ	
A4	DWG NO.	AD00036-7/2	
	REVISION	I R	SHEET 1 of 1